

# N7412-VB Datasheet N-Channel 30-V (D-S) MOSFET

V <sub>DS</sub>	30	V
R <sub>DS(on),typ</sub> V <sub>GS</sub> =10V	13	mΩ
RDS(on),typ VGS=4.5V	19	mΩ
ID	30	Α

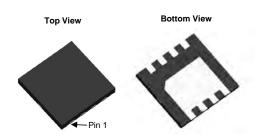
## **FEATURES**

- · Halogen-free
- Trench Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested

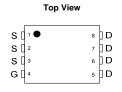


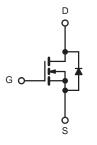
## **APPLICATIONS**

- DC/DC Conversion
  - Low-Side Switch
- Notebook PC
- Gaming



DFN 3x3 EP





N-Channel MOSFET

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	30	V	
Gate-Source Voltage		$V_{GS}$	± 20	V	
	T <sub>C</sub> = 25 °C		30		
Continuous Drain Current (T <sub>.I</sub> = 150 °C)	T <sub>C</sub> = 70 °C	I <sub>D</sub>	20		
Continuous Diam Current (1j = 130 °C)	T <sub>A</sub> = 25 °C	] 'U [	21.5 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C	1	17.1 <sup>b, c</sup>	Α	
Pulsed Drain Current		I <sub>DM</sub>	100		
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	la	13		
	T <sub>A</sub> = 25 °C	ls –	3.1 <sup>b, c</sup>		
Single Pulse Avalanche Current L = 0.1 mH		I <sub>AS</sub>	10		
Avalanche Energy	L = 0.111111	E <sub>AS</sub>	5	mJ	
Maximum Power Dissipation	T <sub>C</sub> = 25 °C		60		
	T <sub>C</sub> = 70 °C	P <sub>D</sub>	30	w	
	T <sub>A</sub> = 25 °C	1 'B f	3.7 <sup>b, c</sup>	VV	
	T <sub>A</sub> = 70 °C	] [	2.4 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 10 s	$R_{thJA}$	27	34	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	6	7.5	C/VV	

#### Notes:

- a. Based on  $T_C = 25$  °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s
- d. Maximum under Steady State conditions is 85 °C/W.



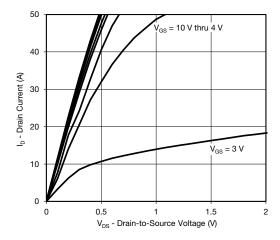
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	30			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I - 250 uA		27		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	- I <sub>D</sub> = 250 μA		- 5.6			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$	1.0		3.0	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zara Cata Valtaga Prain Current		V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V			1	μA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
	В	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A		13		mΩ	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$		19			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 15 A		75		S	
Dynamic <sup>b</sup>				1	<u>I</u>		
Input Capacitance	C <sub>iss</sub>				900	pF	
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0 V, f = 1 MHz			236		
Reverse Transfer Capacitance	C <sub>rss</sub>				20		
Tatal Oata Ohama		$Q_g$ $V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$			20		
Total Gate Charge	$Q_{g}$				9	,,,	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$			2.1	nC	
Gate-Drain Charge	$Q_{gd}$	]			0.7		
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.2	1.1	2.2	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			8	16		
Rise Time	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, R_{L} = 1.5 \Omega$		16	30		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		17	35		
Fall Time	t <sub>f</sub>	1		7	15		
Turn-On Delay Time	t <sub>d(on)</sub>			14	30	ns	
Rise Time	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, R_{L} = 1.5 \Omega$		50	100		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		16	30		
Fall Time	t <sub>f</sub>	]		8	18		
Drain-Source Body Diode Characteristi	cs						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			13		
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				100	A	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 3 A			1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>				40	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	1 10 A dl/dt 100 A/v- T 05 00			20	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		12.5			
Reverse Recovery Rise Time	t <sub>b</sub>	1		7.5		ns	

## Notes:

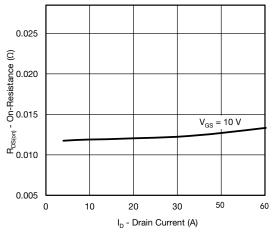
- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 % b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

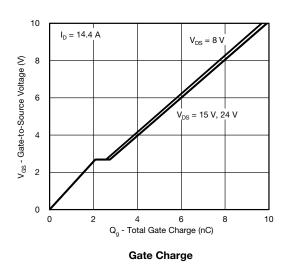


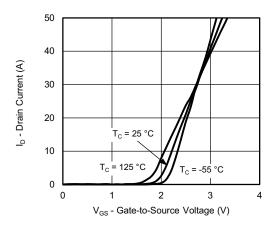


## **Output Characteristics**

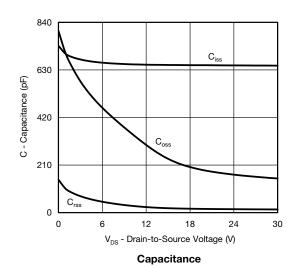


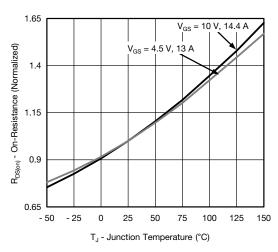
On-Resistance vs. Drain Current





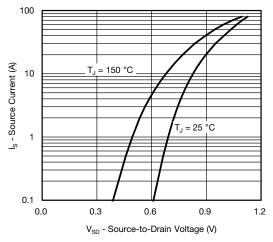
**Transfer Characteristics** 



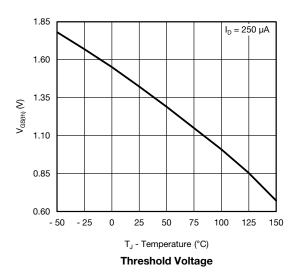


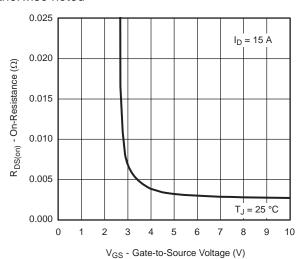
On-Resistance vs. Junction Temperature



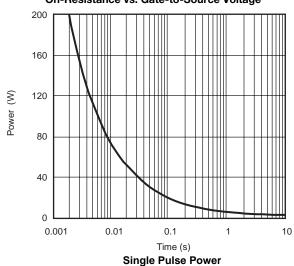


#### **Source-Drain Diode Forward Voltage**





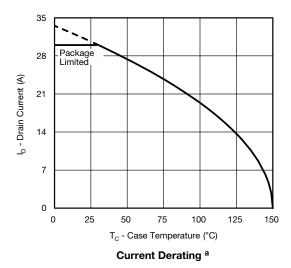
On-Resistance vs. Gate-to-Source Voltage

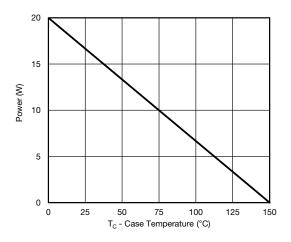


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Safe Operating Area, Junction-to-Ambient





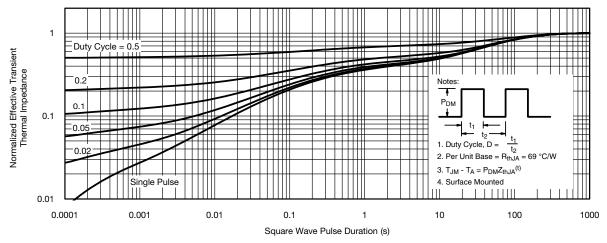


Power, Junction-to-Case

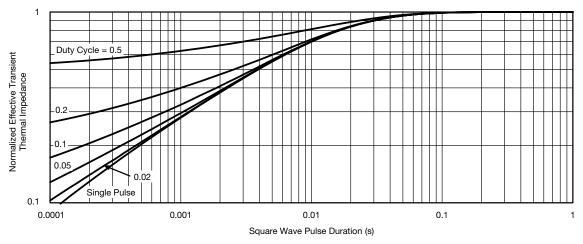
#### Note

a. The power dissipation P<sub>D</sub> is based on T<sub>J</sub> max. = 25 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Ambient

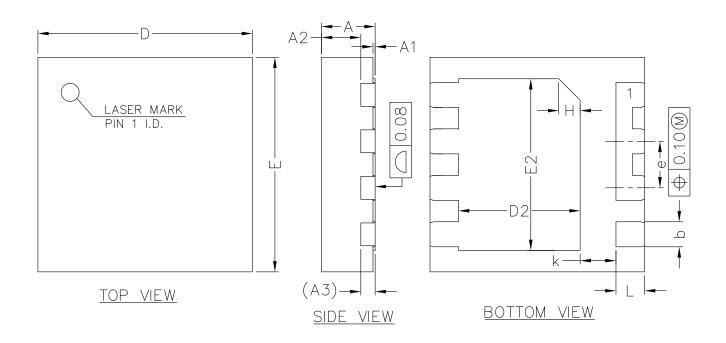


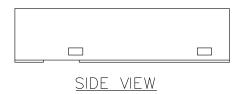
Normalized Thermal Transient Impedance, Junction-to-Case

服务热线:400-655-8788

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COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX	
А	0.70	0.75	0.80	
A1	0.00	0.02	0.05	
A2	0.50	0.55	0.60	
А3	0.20REF			
Ь	0.30	0.35	0.40	
D	2.90	3.00	3.10	
E	2.90	3.00	3.10	
D2	1.60	1.70	1.80	
E2	2.30	2.40	2.50	
е	0.55	0.65	0.75	
K	0.40	0.50	0.60	
L	0.35	0.40	0.45	



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